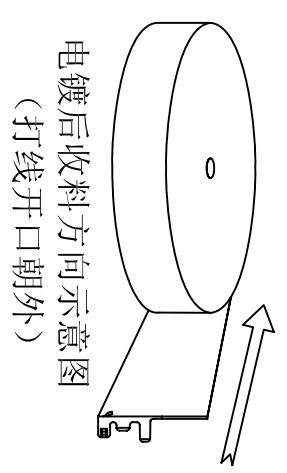
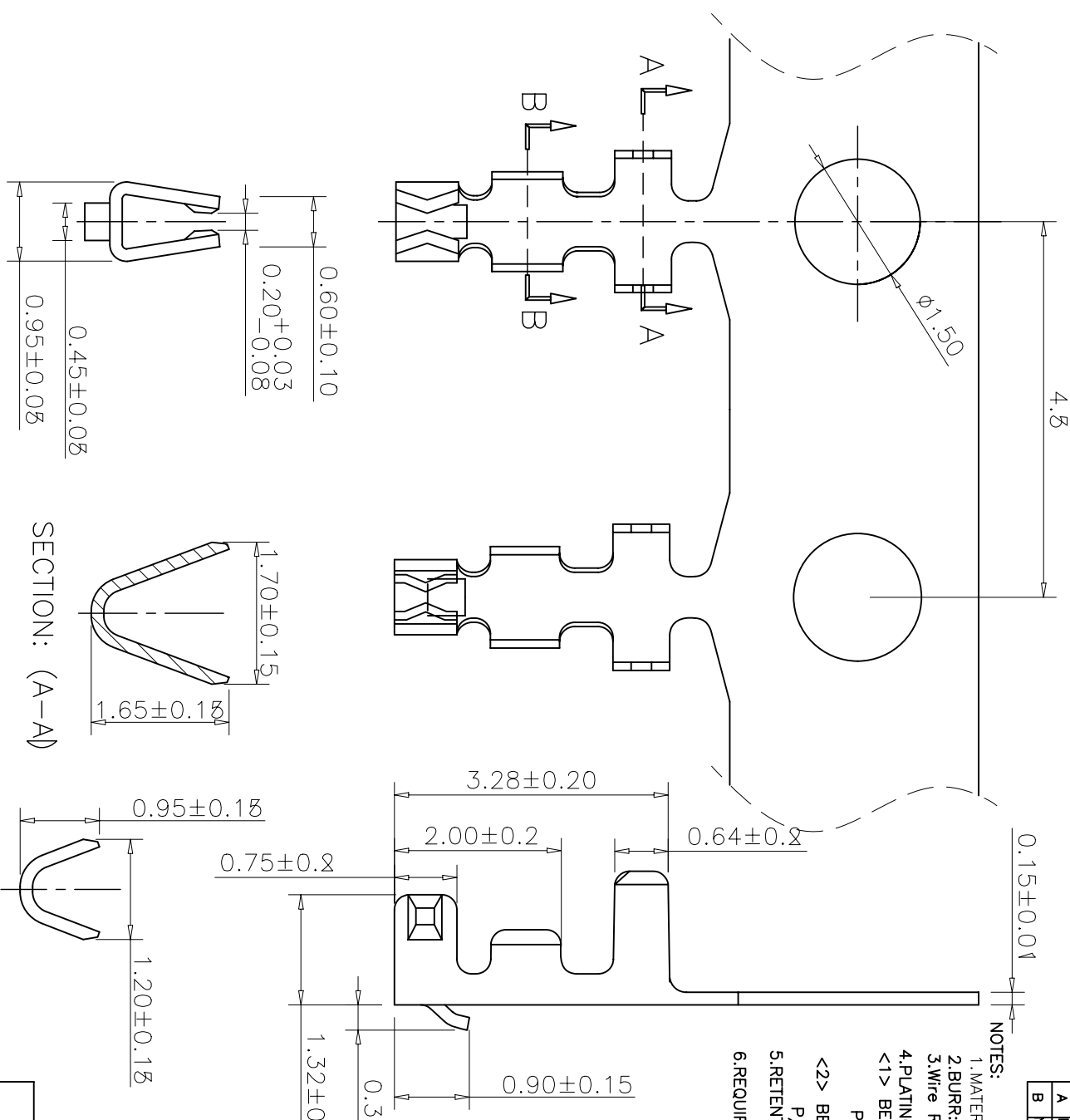


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
A	NAS08-046	变更料号新发行	2008.06.25	郭叫生
B	NAS008-052	修正盐雾试验说明	2008.08.07	郭叫生

NOTES:

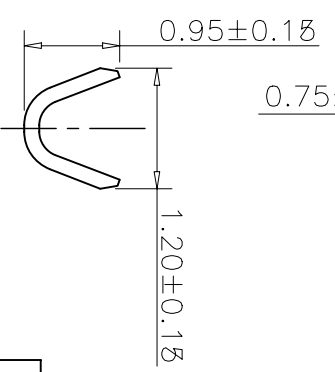
1. MATERIALS: PHOSPHOR BRONZE(C5191-H)
2. BURR: 0.05MAX;WARPAGE: 0.10MAX
3. Wire Range: AWG#28~#32 1.0mm(MAX)OD
4. PLATING:
  - <1> BEFORE PLATING AFTER CLASH: 15u"MIN NI;WHOLE SN: 30u"MIN
  - P/N NO: HS31-PIN001 NO REEK SALT TEST
- 4.2> BECHICS CLASH AFTER PLATING: 20u"MIN NI;WHOLE SN:80u"MIN
- P/N NO: HS31-PIN002 REEK SALT TEST 8H MIN
5. RETENTION FORCE: 1.0kg MIN
6. REQUIRE :
  - cd≤5ppm pd≤50ppm
  - hg≤nd cr≤nd



SECTION: (B-B)

DIM	TOL	DIM	TOL
X	/	X*	/
XX	±0.25	XX*	±2*
XXX	±0.20	XXX*	±1*
KXXX	±0.10	KXXX*	/

SECTION: (A-A)



GXCON ENTERPRISE CO.,LTD.

DRAW NO.	SYMX001T	DATE	P/N NO:	DRAW NAME:
DESIGN	李亚飞	08.01.18	HS31-PIN	MOLEX 1.25 CONTACT
CHECK				
REVIEW				
REV. B			SCALE 1:1	UNIT: mm
				SHEET 1 OF 1